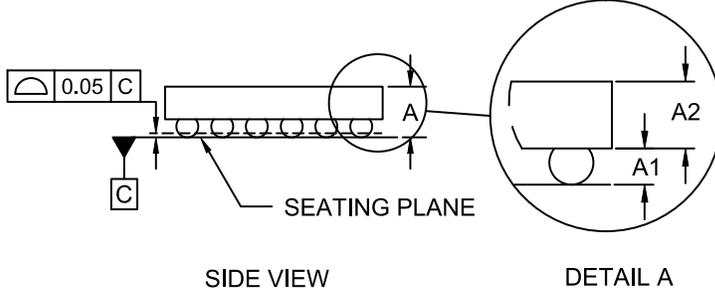
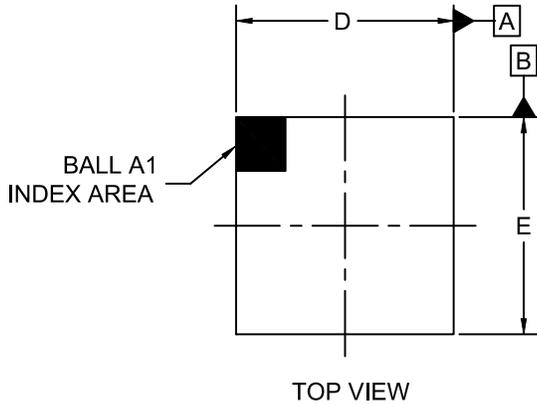


WLCSP36 2.43x2.43x0.4
CASE 567WJ
ISSUE O

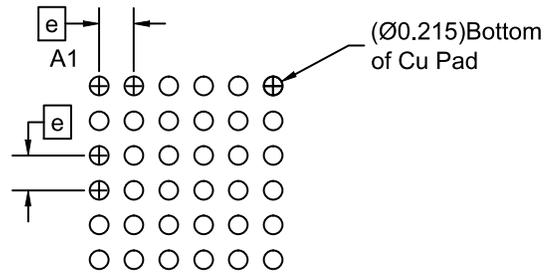
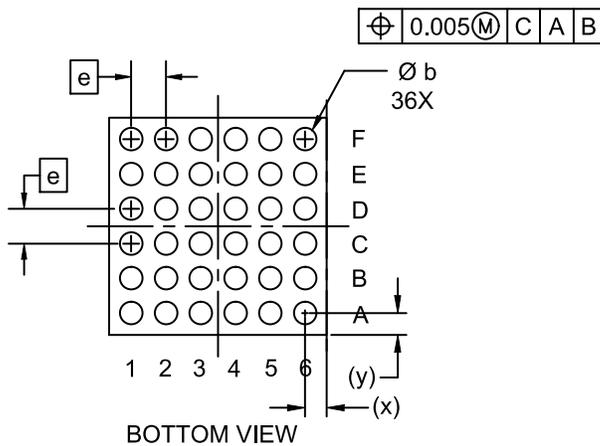
DATE 02 MAY 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C APPLIES TO THE SPHERICAL CROWN OF THE SOLDER BALLS

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.461	0.500	0.539
A1	0.187	0.208	0.229
A2	0.274	0.292	0.310
b	0.240	0.260	0.280
D	2.400	2.430	2.460
E	2.400	2.430	2.460
e	0.40 BSC		
x	0.200	0.215	0.230
y	0.200	0.215	0.230



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